

WAFER-INTERPOSER ASSEMBLY APPARATUS AND METHOD

ABSTRACT

The present invention provides a wafer-interposer assembly apparatus and method. The method for manufacturing the wafer-interposer assembly including the steps of providing a semiconductor wafer and an interposer. The semiconductor wafer including one or more semiconductor die, each semiconductor die having one or more first electrical contact pads. The interposer having one or more communication interfaces and a second electrical contact pad corresponding to each of the one or more first electrical contact pads on each semiconductor die of the semiconductor wafer, and at least one of the second electrical contact pads electrically connected to the one or more communication interfaces. The wafer-interposer assembly is formed by connecting each first electrical contact pad of the semiconductor wafer to the corresponding second electrical contact pad of the interposer with a conductive attachment element. The one or more communication interfaces may include integral edge connector(s) with pins and/or sockets, integral bayonet connector(s) with pins and/or sockets, one or more connectors added to the wafer-interposer assembly, one or more soldered connections, one or more ribbon connectors, one or more RF connectors, one or more optical or infrared connectors, one or more transmit/receive antennas, or one or more clamps or quick release devices.